PRODUCT DATA SHEET

SP_3.0 THERMAL CONDUCTIVITY SOFT SILICON PAD

Last update:14.07.2020r.

This products possess good thermal conductivity and filling properties, softness and elastic characteristics can fill in the air gaps well between hot components and the heat sinks, the metal body and chassis, heat dissipation quickly, promote the work efficiency and extend the service life of equipment.

TECHNICAL CHARACTERISTICS		
Release liner	0,075 PET/0,2 [mm] blue film	
Colour	pink	
TECHNICAL FEATURES		**TEST METHOD**
Thickness	0,3 - 15 [mm] +/- 10%	ASTM D374
Density	2,9 [g/cm³]	ASTM D792
Hardness	55 +/- 5 [Shore 00]	ASTM D2240
Thermal conductivity	3,0 [W/m*K]	ASTM D5470
Thermogravimetric loss	<1,0 [%]	120°C/24hr
Surface resistance	>1,0 *10¹⁴ [Ω]	ASTM D257
Volume resistivity	>1,0 *10¹⁴ [Ω·cm]	ASTM D257
Dielectric strength	>6 [kV/mm]	ASTM D149
Use environment	-40 … +200 [°C]	-
Storage in a cool and dry place (below 25°C)	24 months	-
Size	200*400/ 200*20/ 200*50[mm]	-

Product feature

- Good thermal performance
- Soft and high compressibility, can be a vibration and shock absorber
- Self-adhesive
- Easy assembly
- Electrical insulation
- Meet ROHS and UL environmental requirements
- Provide a variety of thickness
- Halogen Free

Application area

- IC, CPU, graphics processing chip, power electronic capacitors, crystal.
- Diode lights, power supply module, server, the hard disk.
- Plasma displays, LCD monitor, PC, desktop computers, communications equipment, router.
- Memory module, video player, smart phone.

INDUCOMP SP. Z O.O., ul. Ks. Jeremiego 62, 05-080 Izabelin
biuro@inducomp.com.pl; www.inducomp.com.pl